

SG Series









Agency Approvals

AGENCY	AGENCY FILE NUMBER
71 2	E128662

2 Electrode GDT Graphical Symbol



Description

Littelfuse SG series GDT offers high surge ratings in a miniature package. It's designed for surface mounting on PCB with small size 4.5x3.2x2.7mm. Low insertion loss is perfectly suited to broadband equipment applications. The capacitance does not vary with voltage, and will not cause operational problems with ADSL2+, where capacitance variation across Tip and Ring is undesirable. These devices are extremely robust and are able to divert a 1000A pulse without destruction.

Features

- RoHS compliant and Lead-free
- GHz working frequency
- Excellent stability on multiple pulse duty cycle
- Excellent response to fast rising transients.
- Ultra Low Insertion Loss
- 1-2KA surge capability tested with 8/20µS pulse as defined by IEC 61000-4-5
- Ultra small devices offered in a variety of mounting lead forms
- Non-Radioactive
- Low capacitance (<1pF)
- Voltage Ranges 75V to 600V
- UL recognized
- Conforms to ITU-T K12, IEC 1000-4-5
- Square Outline

Applications

- Communication equipment
- CATV equipment
- Test equipment
- Data lines
- Power supplies
- Telecom SLIC protection

- Broadband equipment
- ADSL equipment, including ADSL2+
- XDSL equipment
- Satellite and CATV equipment
- General telecom equipment

Gas Discharge Tube (GDT) Products SG Series

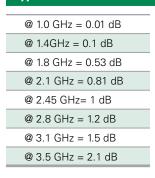
Electrical Characteristics													
	Device Specifications (at 25°C)								Life Ratings				
Part	i	Breako n Volt @100V/		Impulse Breakdown in Volts (@100V/µs)	Impulse Breakdown In Volts (@1 Kv/µsec)	Insulation Resistance		Arc Voltage (@1A)	Glow to Arc Transition Current	Glow Voltage	Nominal AC Discharge Current (x10 @50Hz)	Nominal Impulse Discharge Current (x10 @8/20µs)	Current
Number	MIN	TYP	MAX	MAX		MIN	MAX					(Χ 10 @6/20μ3/	(10/1000µs 100 cycles)
SG75	52	75	98	500	650	>1GΩ (at 50VDC)		~10 V ~10 A		0 A ~60 V	2 A NA*		
SG90	63	90	117	500	600		<1 pf		~1.0 A			2kA	
SG150	105	150	195	500	600			~10 V	10 V ~ 1.0 A				
SG230	172	230	288	650	800								
SG300	225	300	375	700	850			~12 V	~0.5 A	~90 V			
SG300Q	210	300	390	580	650			~20 V	~0.8 A	~140 V			
SG350	263	350	437	750	900		<0.8 pf			~90 V	2 A		10 A
SG350Q	263	350	437	600	700			~12 V	~0.5 A	~0.5 A ~140 V ~90 V	NA*	1kA	10 A
SG400	300	400	500	800	950						2 A		
SG420	315	420	525	800	1000		<1 pf	~10 V		~60 V	2 A		
SG420Q	315	420	525	650	750	>1GΩ (at 100VDC)		~20 V	<1.0 A		NA*		
SG450Q	370	450	550	680	750			~20 V			1 A		
SG500Q	400	500	600	950	1050		<0.5 pf	~16 V	~0.1 A		2 A		
SG6000	450	600	750	1100	1200		<1 pf	~20 V	<0.5 A				

^{*} Specification is not applicable for quick response (SGxxxQ) version of product

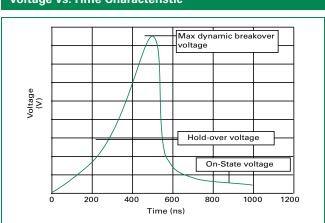
Product Characteristics

Materials	Device Tin Plated 17.5±12.5 Microns Construction Ceramic Insulator.			
Storage and Operational Temperature	-40 to +90 °C			

Typical Insertion Loss



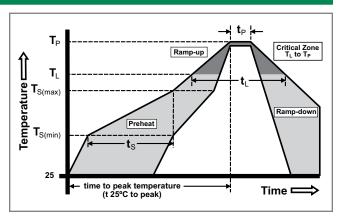
Voltage vs. Time Characteristic



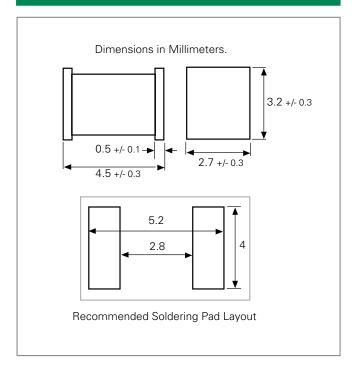


Soldering Parameters - Reflow Soldering (Surface Mount Devices)

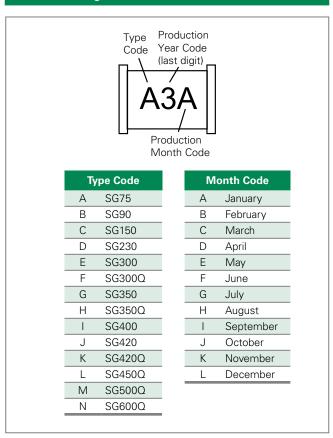
Reflow Co	ndition	Pb – Free assembly		
	-Temperature Min (T _{s(min)})	150°C		
Pre Heat	-Temperature Max (T _{s(max)})	200°C		
	-Time (Min to Max) (t _s)	60 – 180 secs		
Average ra	amp up rate (Liquidus Temp k	3°C/second max		
T _{S(max)} to T _L	- Ramp-up Rate	5°C/second max		
Reflow	-Temperature (T _L) (Liquidus)	217°C		
	-Temperature (t _L)	60 – 150 seconds		
PeakTemp	erature (T _P)	260+ ^{0/-5} °C		
Time with Temperatu	in 5°C of actual peak ıre (t _p)	10 – 30 seconds		
Ramp-dov	vn Rate	6°C/second max		
Time 25°C	to peakTemperature (T _P)	8 minutes Max.		
Do not exc	ceed	260°C		



Device Dimensions



Device Marking



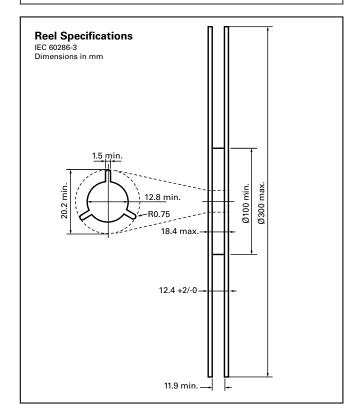


Tape Specifications IEC 60286-3 Dimensions in mm Section A-A 0.4±0.05 A A ± 0.1 A ± 0.1

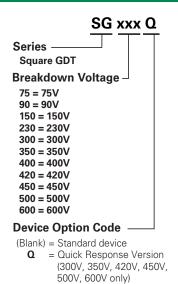
Tape and Reel Dimensions (IEC 60286-3, dimension in mm)



8 ±0.1



Part Numbering System and Ordering Information



Packaging					
Part Num	ber and Device Type	Quantity and Packaging Description			
SGxxx	Surface mount	2000pcs/reel in tape and reel			